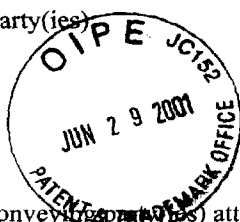


To the Honorable Commissioner of Patents and Trademarks, please record the attached original documents or copy thereof. **101768861**

1. Name of conveying party(ies)

1. Yoshihiro HARA
2. Tetsuo SUZUKI
3. Satoru TAKADA
4. Hidetoshi INOUE

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of Conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

Execution Date: May 30, 2001; May 30, 2001;
May 23, 2001; May 23, 2001

2. Name and address of receiving party(ies):

Name: Kabushiki Kaisha Kobe Seiko Sho (Kobe Steel, Ltd.)

Address: 3-18, Wakinhama-cho 1-chome, Chuo-ku, Kobe-shi, Hyogo 651-0072 Japan

Name: Kobe Precision Inc.

Address: 31031 Huntwood Av.
Hayward, CA 94544 U.S.A.Additional name(s) and address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)
09/384,725

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

**22850**6. Total applications and patents involved: **1**

7. Total fee (37 CFR 3.41): \$40.00

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9. Statement and signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Corwin P. Umbach, Ph.D.

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Corwin Paul Umbach **6-29-01**

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ASSIGNMENT OF APPLICANT

WHEREAS I (WE) Yoshihiro HARA and Tetsuo SUZUKI, of c/o Kobe Corporate Research Laboratories in Kobe Steel, Ltd. 5-5, Takatsukadai 1-chome, Nishi-ku, Kobe-shi, Hyogo 651-2271 Japan, Satoru TAKADA and Hidetoshi INOUE, of c/o KOBE PRECISION INC. 31031 Huntwood Av. Hayward CA 94544 U.S.A., respectively, have invented certain new and useful improvements in:

METHOD FOR RECLAIMING WAFER SUBSTRATE AND POLISHING SOLUTION COMPOSITION FOR RECLAIMING WAFER SUBSTRATE

for which an application for Letters Patent was executed on October 6, 1999 and October 9, 1999 (Application No. 09/384,725, filed August 27, 1999), and

WHEREAS, Kabushiki Kaisha Kobe Seiko Sho (Kobe Steel, Ltd.) having a place of business at: 3-18, Wakinohama-cho 1-chome, Chuo-ku, Kobe-shi, Hyogo 651-0072 Japan, KOBE PRECISION INC. having a place of business at: 31031 Huntwood Av. Hayward CA 94544 U.S.A. (hereinafter referred to as "ASSIGNEE") is/are desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefore in the United States and its territorial possessions and in any and all foreign countries;

NOW, THEREFORE, in consideration of the sum of FIVE DOLLARS (\$5.00), the receipt whereof is hereby acknowledged, and for other good and valuable consideration, I (WE), by these presents do sell, assign and transfer unto said ASSIGNEE, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries and the entire right, title and interest in and to any and all Letters Patent which may be granted therefore in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations, substitutions and renewals thereof.

I (WE) hereby authorize and request the Patent Office Officials in the United States and its territorial possessions and any and all foreign countries to issue any and all of said Letters Patent, when granted, to said ASSIGNEE as the assignee of my (our) entire right, title and interest in and to the same, for the sole use and behalf of said ASSIGNEE, its (his) successors and assigns, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held by me (us) had this Assignment and sale not been made.

Further, I (WE) agree that I (WE) will communicate to said ASSIGNEE or its (his) representatives any facts known to me (us) respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said ASSIGNEE, make all rightful oaths, and generally do everything possible to aid said ASSIGNEE, its (his) successors and assigns, to obtain and enforce proper protection for said invention in the United States and its territorial possessions and in any and all foreign countries.

The undersigned hereby grant(s) the firm of Oblon, Spivak, McClelland, Maier & Neustadt, P.C. of Fourth Floor, 1755 Jefferson Davis Highway, Arlington, Virginia 22202 the power to insert on this assignment any further identification, including the application number and filing date, which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Date May 30, 2001

Yoshihiro Hara
Yoshihiro HARA

Date May 30, 2001

Tetsuo Suzuki
Tetsuo SUZUKI

Date _____

Satoru TAKADA

Date _____

Hidetoshi INOUE

Date _____

Date _____

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Date _____

Date _____

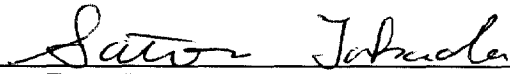
Date _____

Yoshihiro HARA


Date _____

Tetsuo SUZUKI

Date May 23, 2001


Satoru TAKADA

Date May 23, 2001


Hidetoshi INOUE

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